

晶采光電科技股份有限公司 AMPIRE AMPIRE CO., LTD.

SPECIFICATIONS FOR LCD MODULE

CUSTOMER	
CUSTOMER PART NO.	
AMPIRE PART NO.	AC-162B
APPROVED BY	
DATE	

AMPIRE CO., LTD. TOWER A, 4F, No.114, Sec. 1, HSIN-TAI 5th RD., HIS-CHIH, TAIPEI HSIEN, TAIWAN(R.O.C.)

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APPROVED BY	CHECKED BY	ORGANIZED BY

RECORD OF REVISION

Revision Date	Page	Contents
1999/10/6	-	New Release

1 FEATURES

(1) Display format : 16 characters \times 2 lines

(2) Construction: TN/STN LCD panel, Bezel, Zebra and PCB.

(3) Optional Edge/Array LED or EL back-light.

(4) Controller: SED1278 or Equivalent.

(5) 5V single power input. (Special request for 3.3V driving, built-in DC/DC converter.)

(6) Normal / Extended temperature type.

(7) Excellent LC: VOP maintains at 5V for whole temp. range, no need extra temp. compensation circuit.

2 NUMBERING SYSTEM

No	Code Value	Description	Remark
1	N	TN type LCD	LCD Type
	G	STN gray type LCD	
	Y	STN yellow green type LCD	
	S	STN negative type LCD	
2	A	Reflective type / 6:00 view	Polarizer / Viewing Angel
	В	Reflective type / 12:00 view	
	I	Transflective type / 6:00 view	
	J	Transflective type / 12:00 view	
	T	Negative type / 6:00 view	
	U	Negative type / 12:00 view	
3	None	Without backlight	Backlight type
	Q	Edge type LED	
	L	Array type 5V LED	
	Е	EL	
4	None	Without backlight	Backlight color
	Y	Yellow-green (LED)	
	В	Blue (EL)	
	W	White (EL)	
5	None	Normal temperature type	LCM temperature type
	Н	Extended temperature type	

3 MECHANICAL DATA

Parameter	Stand Value	Unit
Dot size	$0.55(W) \times 0.65(H)$	mm
Dot pitch	$0.60(W) \times 0.70(H)$	mm
Character size	$2.95(W) \times 5.55(H)$	mm
Viewing area	64.0(W) × 17.2(H)	mm
Module size	$80.0(W) \times 36.0(H) \times 10.0 \text{ max (T)}$	mm
Module size (Edge LED back-light)	$80.0(W) \times 36.0(H) \times 11.0 \text{ max (T)}$	mm
Module size (Array LED back-light)	$80.0(W) \times 36.0(H) \times 14.5 \text{ max (T)}$	mm

4 ABSOLUTE MAXIMUM RATINGS

Para	meter	Symbol	Min	Max	Unit
Logic Circuit	VDD-VSS	-0.3	7.0	V	
LCD Driv	VDD-VO	-0.3	10.0	V	
Input Voltage		VI	-0.3	VDD+0.3	V
Normal temp. type	Operating Temp.	ТОР	0	50	°C
	Storage Temp.	TSTG	-20	70	°C
Extended temp. type	Operating Temp.	ТОР	-20	70	°C
	Storage Temp.	Tstg	-30	80	°C

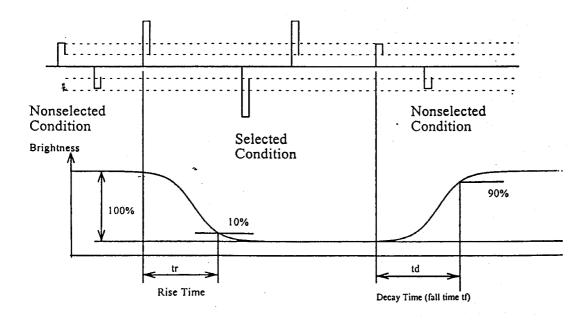
5 ELECTRO-OPTICAL CHARACTERISTICS

Parameter	Symbol	Condition	Min	Тур	Max	Unit	Note
		Electro	nic Chara	cteristics			
Logic Circuit Supply Voltage	VDD-VSS		2.7		5.5	V	
LCD Driving	VDD-VO	0 °C	4.4	4.7	5.0	V	TN type LCD
Voltage		25 °C	4.2	4.5	4.8		could only be operated on
(TN)		50 °C	3.9	4.2	4.5		Normal Temp.
LCD Driving	VDD-VO	-20 °C	4.75	5.0	5.25	V	0 ~ 50 °C for
Voltage		0 °C	4.75	5.0	5.25		Normal Temp. type
(STN)		25 °C	4.75	5.0	5.25		-20 ~ 70 °C for
		50 °C	4.75	5.0	5.25		Extended Temp.
		70 °C	4.75	5.0	5.25		type
Input Voltage	VIH		0.7 VDD		VDD	V	
	VIL		VSS		0.3 VDD	V	
Logic Supply Current	IDD	VDD = 5V		1.0	1.5	mA	
		Optical C	haracteris	stics (TN	1)		
Contrast	CR	25°C		3			Note 1
Rise Time	tr	25°C		150		ms	Note 2
Fall Time	tf	25°C		150		ms	
Viewing Angle	θf	25°C &		35			Note 3
Range	θЬ	CR≥1.4		10		Deg.	
	θ1			30			
	θr			30			
Frame Frequency	fF	25°C		64		Hz	
		- Optical Cl	haracteris	tics (STI	V)		
Contrast	CR	25°C		5			Note 1
Rise Time	tr	25°C		80	120	ms	Note 2
Fall Time	tf	25°C		150	300	ms	
Viewing Angle	θf	25°C &		40			Note 3
Range	θЬ	CR≥2		35		Deg.	
	θ1			35			
	θr			35			
Frame Frequency	fF	25°C		64		Hz	

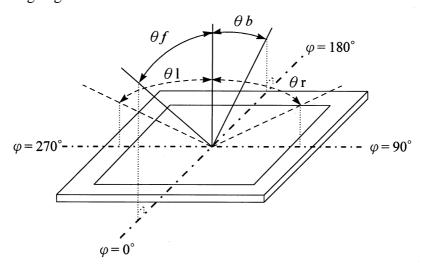
(NOTE 1) Contrast ratio:

CR = (Brightness in OFF state) / (Brightness in ON state)

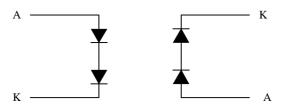
(NOTE 2) Response time :



(NOTE 3) Viewing angle

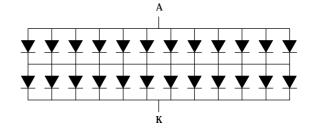


Edge type LED Back-light Characteristics								
Parameter	Symbol	Condition	Min	Тур	Max	Unit	Note	
Forward Voltage	VF		1	4.05	4.3	V	Supply Voltage between A&K	
Forward Current	IF	VF=4.05V		20		mA		
Bare LED Lumin	ous intensity	VF=4.05V		25		cd/m ²		
LCM Luminou	s intensity	VF=4.05V		8		cd/m ²		



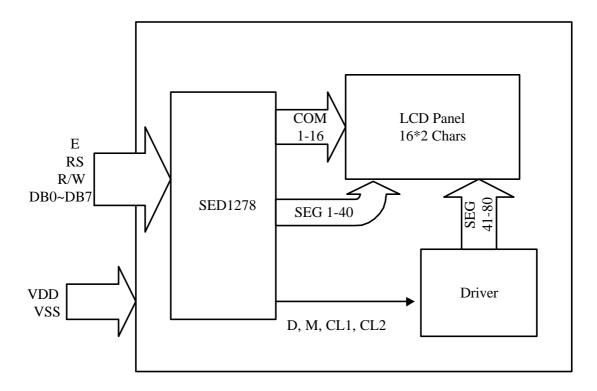
Array type LED Back-light Characteristics								
Parameter	Symbol	Condition	Min	Тур	Max	Unit	Note	
Forward Voltage	VF			4.05	4.3	V	Supply Voltage between A&K	
Forward Current	IF	VF=4.05V		120	1	mA		
Bare LED Lumin	ous intensity	VF=4.05V		100		cd/m ²		
LCM Luminou	s intensity	VF=4.05V		30		cd/m ²		

* LED Dice number = $2 \times 12 = 24$



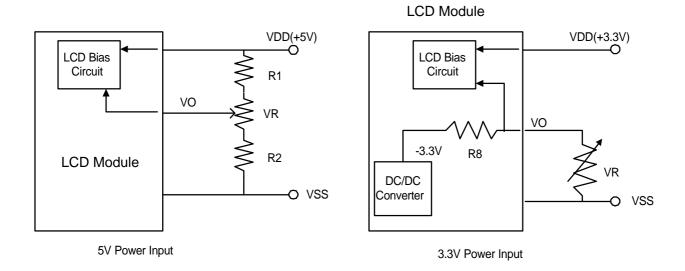
EL Back-light Characteristics							
Parameter Min Typ Max Unit Note							
Driving Voltage	1	110		Vrms			
Frequency		400		Hz			
Bare EL Luminous intensity		45		cd/m ²			
LCM Luminous intensity		15		cd/m ²			

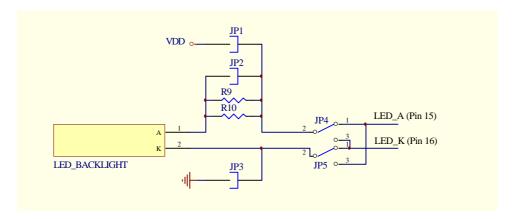
6 BLOCK DIAGRAM & INTERFACE



No.	Symbol	Function
1	VSS	Ground (0V)
2	VDD	Supply Voltage for Logic (+5V or +3.3V)
3	VO	Contrast Adjustment
4	RS	Data/Instruction Select
5	R/W	Read/Write Select
6	Е	Enable Signal
7	DB0	Data Bus
8	DB1	Data Bus
9	DB2	Data Bus
10	DB3	Data Bus
11	DB4	Data Bus
12	DB5	Data Bus
13	DB6	Data Bus
14	DB7	Data Bus
15	LED_A	LED Power Supply + (5V)
16	LED_K	LED Power Supply - (5V)

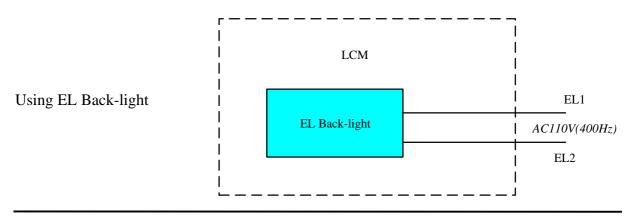
7 POWER SUPPLY





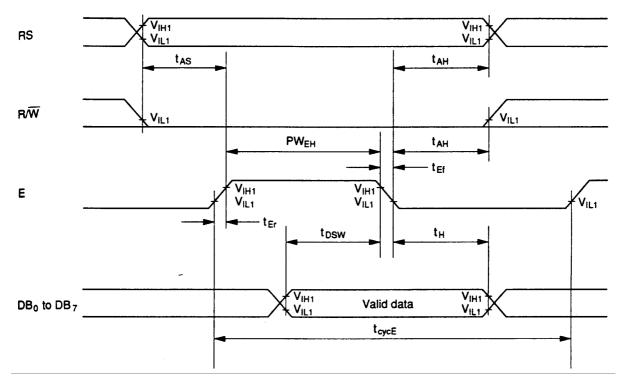
There are four methods to light up the LED back-light: (Please indicate while ordering.)

- (1) Built-in current-limit resistor(R9/R10). Add +5V between Pin15&16. (Default)
- (2) Add +4.05V between LED A & K directly.
- (3) Short JP2 and add +4.05V between Pin15&16.
- (4) Built-in current-limit resistor(R9/R10) and short JP1&JP3. Use the same power (+5V) with the logic circuit.



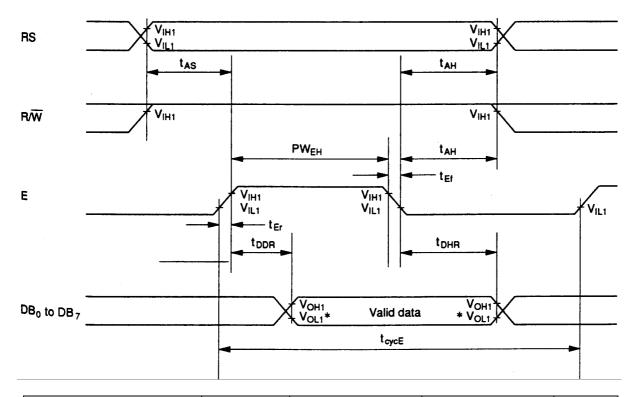
8 TIMING CHARACTERISTICS

Write Operation



Item	Symbol	VDD=5V		VDD:	=3.3V	Unit
		Min	Max	Min	Max	
Enable cycle time	tcycE	500		1000		ns
Enable pulse width	PWEH	230		450		
Enable rise/fall time	tEr,tEf		20		25	
Address set-up time (RS, R/W to E)	tAS	40		60		
Address hold time	tAH	10		20		
Data set-up time	tDSW	80		195		
Data hold time	tH	10		10		

Read Operation



Item	Symbol	VDI)=5V	VDD	Unit	
		Min	Max	Min	Max	
Enable cycle time	tcycE	500		1000		ns
Enable pulse width	PWEH	230		450		
Enable rise/fall time	tEr,tEf		20		25	
Address set-up time (RS, R/W to E)	tAS	40		60		
Address hold time	tAH	10		20		
Data delay time	tDDR		120		360	
Data hold time	tDRH	5		5		

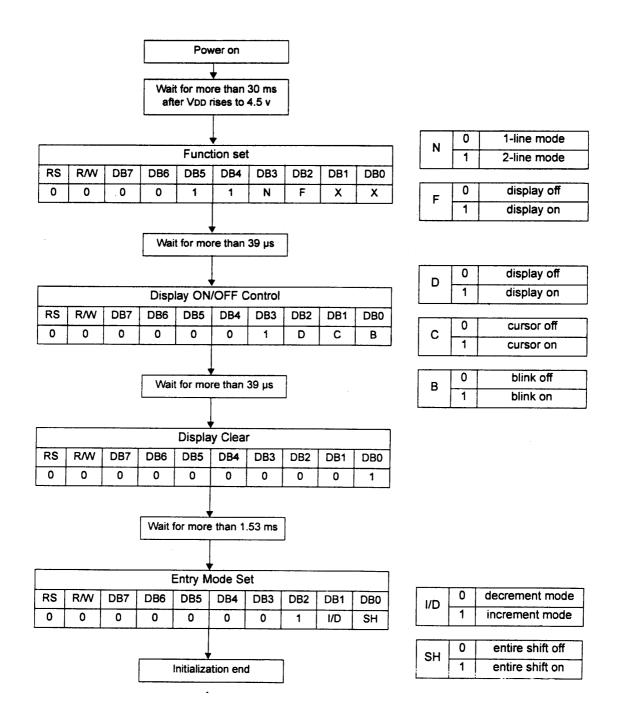
9 INSTRUCTION SET

Instruction	Code									Description	E.T.(fosc	
	RS	R/ W	D7	D6	D5	D4	D3	D2	D1	D0		=270 KHZ)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write"20H" to DDRAM and set DDRAM address to "00H" from AC	1.53 ms
Return Home	0	0	0	0	0	0	0	0	1		Sets DD RAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.53 ms
Entry Mode SET	0	0	0	0	0	0	0	1	I/D	SH	Assign cursor moving direction and enable the shift of entire display.	39 μS
Display ON/OFF Control	0	0	0	0	0	0	1	D	С	В	Set display (D), cursor (C), and blink of cursor (B) on/off control bit.	39 μS
Cursor or Display Shift	0	0	0	0	0	1	S/ C	R/ L			Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data.	39 μS
Function Set	0	0	0	0	1	DL	N	F			Sets interface data length (DL:8-bit/4-bit), number of display lines (N:2-line/1-line) and , display font type (F:5x11dots/5x8 dost).	39 μS
Set CG RAM Address	0	0	0	1	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Sets CG RAM address in address counter.	39 μS
Set DD RAM Address	0	0	1	AC 6	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Sets DD RAM address in address counter.	39 μS
Read Busy Flag and Address	0	1	BF	AC 6	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0 μS
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Writes data into internal RAM (DD RAM /CG RAM).	43 μS
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Reads data from internal RAM (DD RAM /CG RAM).	43 μS

* "--": don't care

Note: When an MPU program with checking the Busy Flag(DB7) is made, it must be necessary 1/2 Fosc is necessary for executing the next instruction by the falling edge of the 'E' signal after the Busy Flag(DB7) goes to "LOW".

10 INITIALIZATION SEQUENCE



11 DD RAM ADDRESS

DIGIT	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
1 LINE	00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F
2 LINE	40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F

DD RAM Address

12 FONT TABLE

		Higher 4-bit (D4 to D7) of Character Code (Hexadecimal)															
		0	1	2	3	4	5	6	7	8	9	A	В	С	Ď	Е	F
	0	CG RAM (1)					::::	••						٠	:		
	1	CG RAM (2)			i.			-:::				:			:		
	2	CG RAM (3)		**				i:					====	****	::		•
	3	CG RAM (4)				····	•	:					:	!. !	::		
	4	CG RAM (5)										:	:	:			
decimal)	5	CG RAM (6)		•••	:	!		::::	ii					::::	-:		
ode (Hexa	6	CG RAM (7)					!!		ii						••••		
aracter Cc	7	CG RAM (8)		:	:			-::::	!!				::::	-;::		•	
D3) of Ch	8	CG RAM (1)		•				!···					ŀ	-::			
Lower 4-bit (D0 to D3) of Character Code (Hexadecimal)	9	CG RAM (2)		.:			:::	:	••			•		::	-#-		
Lower 4-	Α	CG RAM (3)		***	::	!		:					l::	::	•	:::	
	В	CG RAM (4)			::								.;;;	:: ::		:::-	
	С	CG RAM (5)		:		<u></u>							··i		-#-		•
	D	CG RAM (6)						:::i				1	 	: <u>.</u>			
	Е	CG RAM (7)		==			"	!·":								• • •	
	F	CG RAM (8)		.•••	••••			::::					:::	#:	**	::::	

^{*} Character codes (00H-0FH) of SED1278F are assigned to the area of character generator RAM (CG RAM). The CG ROM of the SED1278F is masked; if you wish to have your own CG ROM, consult S-MOS Marketing Department for conversion of the masked ROM.

13 QUALITY AND RELIABILITY

13.1 TEST CONDITIONS

Tests should be conducted under the following conditions:

Ambient temperature : $25 \pm 5^{\circ}$ C

Humidity : $60 \pm 25\%$ RH.

13.2 SAMPLING PLAN

Sampling method shall be in accordance with MIL-STD-105E, inspection level II, normal inspection, and single sampling plan tables for normal, tightened, and reduced inspection.

13.3 ACCEPTABLE QUALITY LEVEL

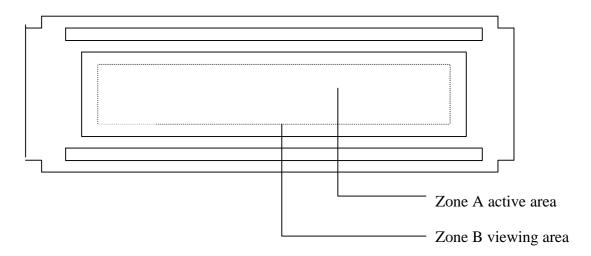
A major defect is defined as one that could cause failure to or materially reduce the usability of the unit for its intended purpose. A minor defect is one that does not materially reduce the usability of the unit for its intended purpose or is an infringement from established standards and has no significant bearing on its effective use or operation.

13.4 APPEARANCE

An appearance test should be conducted by human sight at approximately 30 cm distance from the LCD module under flourescent light. The inspection area of LCD panel shall be within the range of following limits.

13.5 INSPECTION QUALITY CRITERIA

Item	Description	of def	fects		Class of Defects	Acceptable level
Function	Short circuit of	Major	0.65			
Dimension	Deviation from	m drawi	ngs		Major	1.5
Black spots	Ave . dia . D	area A	A	area B	Minor	2.5
1	D≤0.2		isrega	ırd		
	0.2 <d≤0.3< td=""><td>3</td><td></td><td>4</td><td></td><td></td></d≤0.3<>	3		4		
	0.3 <d≤0.4< td=""><td>2</td><td></td><td>3</td><td></td><td></td></d≤0.4<>	2		3		
	0.4 <d< td=""><td>0</td><td></td><td>1</td><td></td><td></td></d<>	0		1		
Black lines	Width W, Length 1	Ĺ	A	В	Minor	2.5
	W≤0.03		disı	egard		
	0.03 <w≤0.05< td=""><td></td><td>3</td><td>4</td><td></td><td></td></w≤0.05<>		3	4		
	0.05 <w≤0.07 ,="" l≤3<="" td=""><td>3.0</td><td>1</td><td>1</td><td></td><td></td></w≤0.07>	3.0	1	1		
	See line	criteria				
Bubbles in	Average diameter D	0.2 < I	0 < 0.5	5 mm	Minor	2.5
polarizer	for $N = 4$, $D >$	0.5 for 1	N = 1			
Color	Rainbow color o	r newto	n ring		Minor	2.5
uniformity						
Glass	Obvious visib	ole dama	age.		Minor	2.5
Scratches						
Contrast	See no		Minor	2.5		
ratio						
Response	See no	Minor	2.5			
time						
Viewing	See no		Minor	2.5		
angle						



13.6 RELIABILITY

	Test Conditions							
Test Item	Normal Temp. type	Extended Temp. type	Note					
High Temperature Operation	50±3°C, t=96 hrs	70±3°C, t=96 hrs						
Low Temperature Operation	0±3°C, t=96 hrs	-20±3°C, t=96 hrs						
High Temperature Storage	70±3°C, t=96 hrs	80±3°C, t=96 hrs	1,2					
Low Temperature Storage	-20±3°C, t=96 hrs	-30±3°C, t=96 hrs	1,2					
Thermal Shock Test	`		1,2					
Humidity Test	40 °C, Humidity 90%, 96 hrs							
Sweep frequency: 10 ~ 55 ~ 10 Hz/1min Amplitude: 0.75mm Test direction: X.Y.Z/3 axis Duration: 30min/each axis								

Note 1: Condensation of water is not permitted on the module.

Note 2 : The module should be inspected after 1 hour storage in normal conditions $(15-35^{\circ}\text{C}, 45-65\%\text{RH})$.

Definitions of life end point :

- Current drain should be smaller than the specific value.
- Function of the module should be maintained.
- Appearance and display quality should not have degraded noticeably.
- Contrast ratio should be greater than 50% of the initial value.

14 HANDLING PRECAUTIONS

- (1) An LCD module is a fragile item and should not be subjected to strong mechanical shocks.
- (2) Avoid applying pressure to the module surface. This will distort the glass and cause a change in colour.
- (3) Under no circumstances should the position of the bezel tabs or their shape be modified.
- (4) Do not modify the display PCB in either shape or positioning of components.
- (5) Do not modify or move location of the zebra or heat seal connectors.
- (6) The device should only be soldered to during interfacing. Modification to other areas of the board should not be carried out.
- (7) In the event of LCD breakage and resultant leakage of fluid do not inhale, ingest or make contact with the skin. If contact is made rinse immediately.
- (8) When cleaning the module use a soft damp cloth with a mild solvent, such as Isopropyl or Ethyl alcohol. The use of water, ketone or aromatic is not permitted.
- (9) Prior to initial power up input signals should not be applied.
- (10) Protect the module against static electricity and observe appropriate anti-static precautions.

15 OUTLINE DIMENSION

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